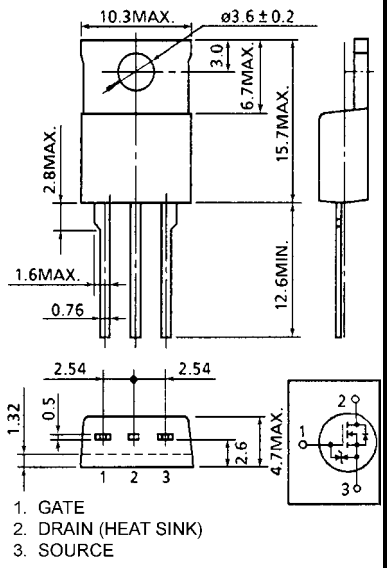
TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π−MOSIII)

# 2SK2733

Chopper Regulator, DC−DC Converter and Motor Drive Applications

- Low drain−source ON resistance : $R_{DS\ (ON)}$ = 8.0 Ω (typ.)
- High forward transfer admittance : $|Y_{fs}|$ = 0.9 S (typ.)
- Low leakage current : $I_{DSS}$ = 100 μA (max) ($V_{DS}$ = 720 V)
- Enhancement−mode : $V_{th}$ = 2.0~4.0 V ($V_{DS}$ = 10 V, $I_D$ = 1 mA)

Unit: mm




| | |
|---|---|
| JEDEC | TO-220AB |
| JEITA | SC-46 |
| TOSHIBA | 2-10P1B |

Weight: 2.0 g (typ.)

## Maximum Ratings (Ta = 25°C)

| Characteristics | | Symbol | Rating | Unit |
|---|---|---|---|---|
| Drain−source voltage | | $V_{DSS}$ | 900 | V |
| Drain−gate voltage ($R_{GS}$ = 20 kΩ) | | $V_{DGR}$ | 900 | V |
| Gate−source voltage | | $V_{GSS}$ | ±30 | V |
| Drain current | DC (Note 1) | $I_D$ | 1 | A |
| | Pulse (Note 1) | $I_{DP}$ | 3 | |
| Drain power dissipation (Tc = 25°C) | | $P_D$ | 60 | W |
| Single pulse avalanche energy (Note 2) | | $E_{AS}$ | 324 | mJ |
| Avalanche current | | $I_{AR}$ | 1 | A |
| Repetitive avalanche energy (Note 3) | | $E_{AR}$ | 6.0 | mJ |
| Channel temperature | | $T_{ch}$ | 150 | °C |
| Storage temperature range | | $T_{stg}$ | −55~150 | °C |

## Thermal Characteristics

| Characteristics | Symbol | Max | Unit |
|---|---|---|---|
| Thermal resistance, channel to case | $R_{th\ (ch-c)}$ | 2.08 | °C / W |
| Thermal resistance, channel to ambient | $R_{th\ (ch-a)}$ | 83.3 | °C / W |

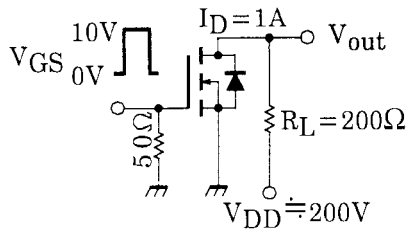
Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: $V_{DD}$ = 90 V, $T_{ch}$ = 25°C (initial), L = 594 mH, $R_G$ = 25 Ω, $I_{AR}$ = 1 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.
Please handle with caution.

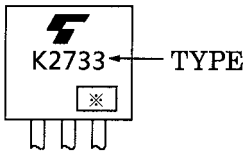
## Electrical Characteristics (Ta = 25°C)

| Characteristics | | Symbol | Test Condition | Min | Typ. | Max | Unit |
|---|---|---|---|---|---|---|---|
| Gate leakage current | | $I_{GSS}$ | $V_{GS}$ = ±30 V, $V_{DS}$ = 0 V | — | — | ±10 | μA |
| Gate−source breakdown voltage | | $V_{(BR)\ GSS}$ | $I_G$ = ±10 μA, $V_{DS}$ = 0 V | ±30 | — | — | V |
| Drain cut−off current | | $I_{DSS}$ | $V_{DS}$ = 720 V, $V_{GS}$ = 0 V | — | — | 100 | μA |
| Drain−source breakdown voltage | | $V_{(BR)\ DSS}$ | $I_D$ = 10 mA, $V_{GS}$ = 0 V | 900 | — | — | V |
| Gate threshold voltage | | $V_{th}$ | $V_{DS}$ = 10 V, $I_D$ = 1 mA | 2.0 | — | 4.0 | V |
| Drain−source ON resistance | | $R_{DS\ (ON)}$ | $V_{GS}$ = 10 V, $I_D$ = 0.5 A | — | 8.0 | 9.0 | Ω |
| Forward transfer admittance | | $\|Y_{fs}\|$ | $V_{DS}$ = 20 V, $I_D$ = 0.5 A | 0.2 | 0.9 | — | S |
| Input capacitance | | $C_{iss}$ | $V_{DS}$ = 25 V, $V_{GS}$ = 0 V, f = 1 MHz | — | 370 | — | pF |
| Reverse transfer capacitance | | $C_{rss}$ | | — | 5 | — | |
| Output capacitance | | $C_{oss}$ | | — | 40 | — | |
| Switching time | Rise time | $t_r$ |   Duty ≤ 1%, $t_w$ = 10μs | — | 20 | — | ns |
| | Turn−on time | $t_{on}$ | | — | 70 | — | |
| | Fall time | $t_f$ | | — | 30 | — | |
| | Turn−off time | $t_{off}$ | | — | 95 | — | |
| Total gate charge (gate−source plus gate−drain) | | $Q_g$ | $V_{DD}$ ≈ 400 V, $V_{GS}$ = 10 V, $I_D$ = 1 A | — | 15 | — | nC |
| Gate−source charge | | $Q_{gs}$ | | — | 6 | — | |
| Gate−drain (“miller”) Charge | | $Q_{gd}$ | | — | 9 | — | |

## Source−Drain Ratings and Characteristics (Ta = 25°C)

| Characteristics | Symbol | Test Condition | Min | Typ. | Max | Unit |
|---|---|---|---|---|---|---|
| Continuous drain reverse current (Note 1) | $I_{DR}$ | — | — | — | 1 | A |
| Pulse drain reverse current (Note 1) | $I_{DRP}$ | — | — | — | 3 | A |
| Forward voltage (diode) | $V_{DSF}$ | $I_{DR}$ = 1 A, $V_{GS}$ = 0 V | — | — | −1.9 | V |
| Reverse recovery time | $t_{rr}$ | $I_{DR}$ = 1 A, $V_{GS}$ = 0 V<br>$dI_{DR}$ / dt = 100 A / μs | — | 750 | — | ns |
| Reverse recovery charge | $Q_{rr}$ | | — | 3 | — | μC |

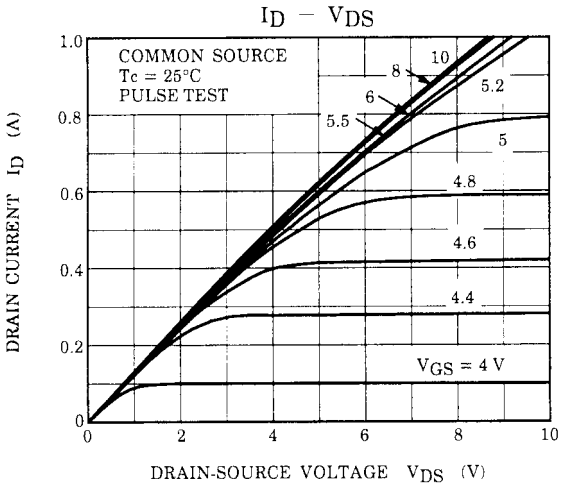
## Marking

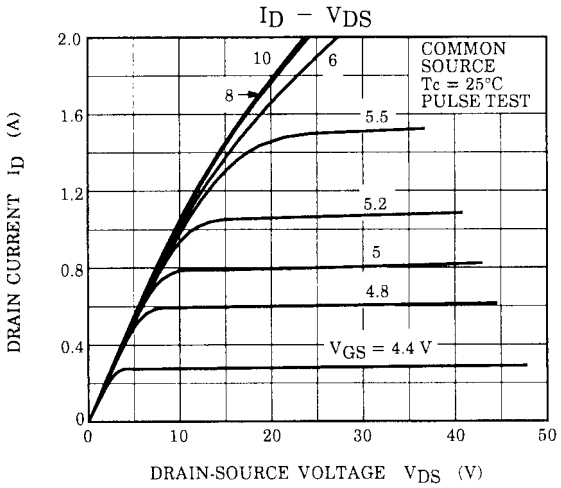


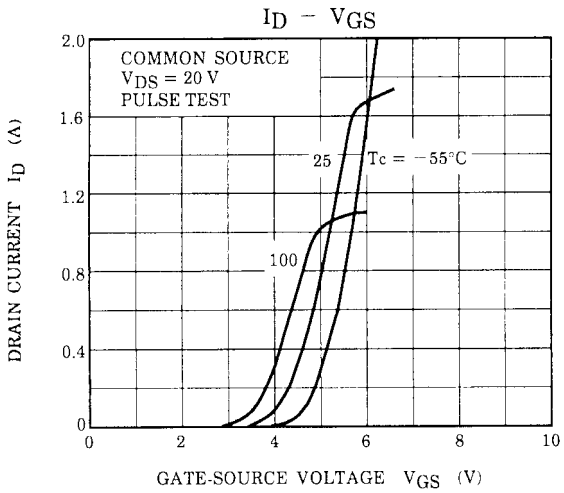

※ Lot Number

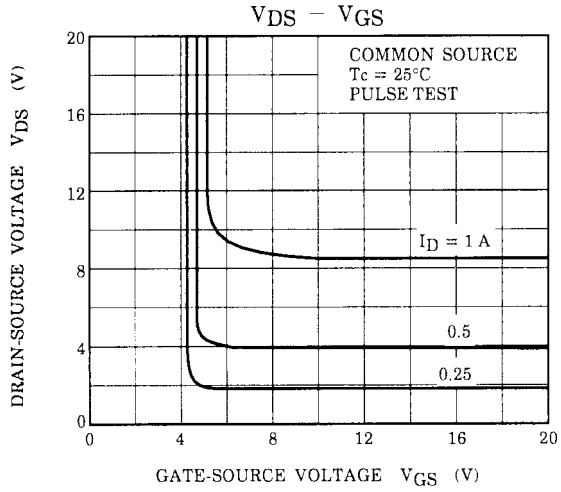
□□ — Month (Starting from Alphabet A)

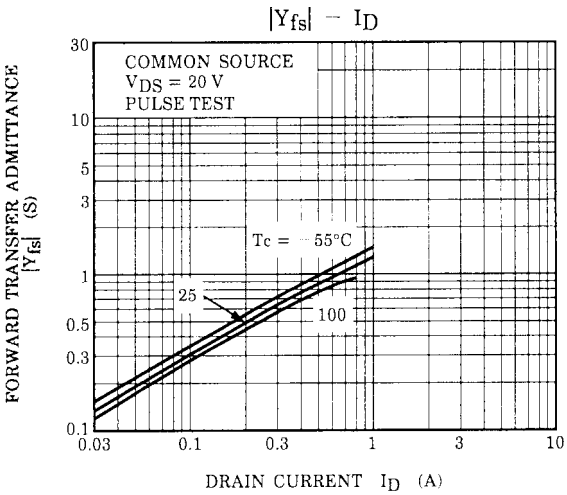
— Year (Last Number of the Christian Era)

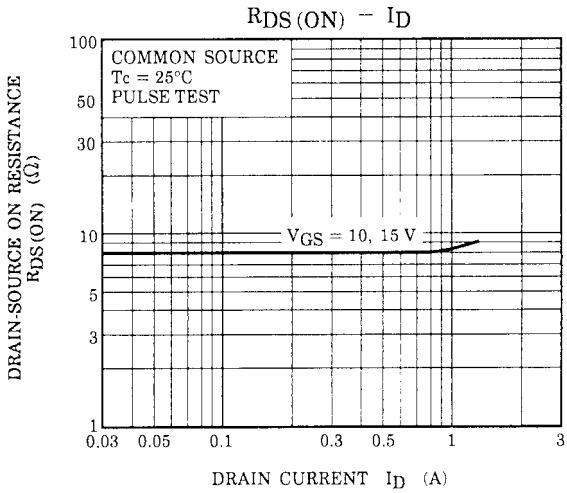

$I_D$ – $V_{DS}$
COMMON SOURCE
Tc = 25°C
PULSE TEST
10
8
6
5.5
5.2
5
4.8
4.6
4.4
$V_{GS}$ = 4 V
DRAIN CURRENT $I_D$ (A)
DRAIN-SOURCE VOLTAGE $V_{DS}$ (V)


$I_D$ – $V_{DS}$
COMMON SOURCE
Tc = 25°C
PULSE TEST
10
8
6
5.5
5.2
5
4.8
$V_{GS}$ = 4.4 V
DRAIN CURRENT $I_D$ (A)
DRAIN-SOURCE VOLTAGE $V_{DS}$ (V)

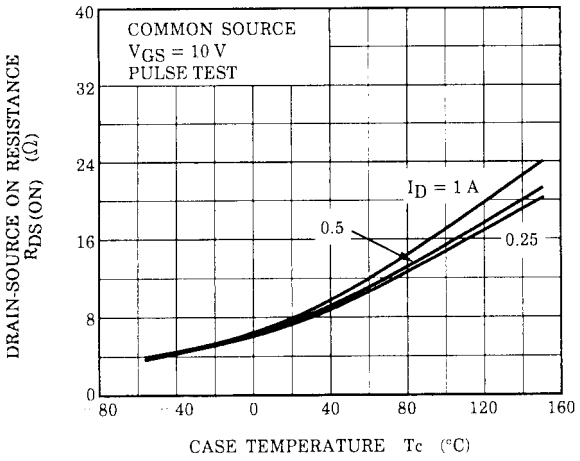

$I_D$ – $V_{GS}$
COMMON SOURCE
$V_{DS}$ = 20 V
PULSE TEST
25
Tc = −55°C
100
DRAIN CURRENT $I_D$ (A)
GATE-SOURCE VOLTAGE $V_{GS}$ (V)


$V_{DS}$ – $V_{GS}$
COMMON SOURCE
Tc = 25°C
PULSE TEST
$I_D$ = 1 A
0.5
0.25
DRAIN-SOURCE VOLTAGE $V_{DS}$ (V)
GATE-SOURCE VOLTAGE $V_{GS}$ (V)

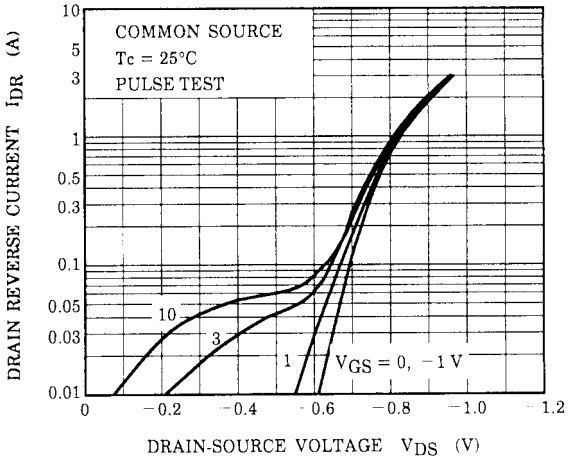

$|Y_{fs}|$ – $I_D$
COMMON SOURCE
$V_{DS}$ = 20 V
PULSE TEST
Tc = −55°C
25
100
FORWARD TRANSFER ADMITTANCE $|Y_{fs}|$ (S)
DRAIN CURRENT $I_D$ (A)


$R_{DS\,(ON)}$ – $I_D$
COMMON SOURCE
Tc = 25°C
PULSE TEST
$V_{GS}$ = 10, 15 V
DRAIN-SOURCE ON RESISTANCE $R_{DS\,(ON)}$ (Ω)
DRAIN CURRENT $I_D$ (A)

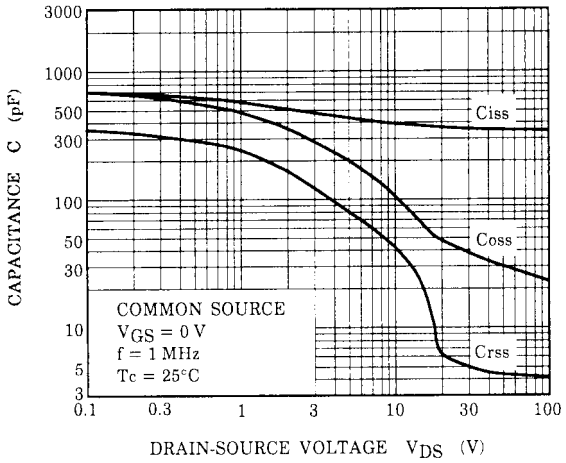
$R_{DS\,(ON)}$ – Tc



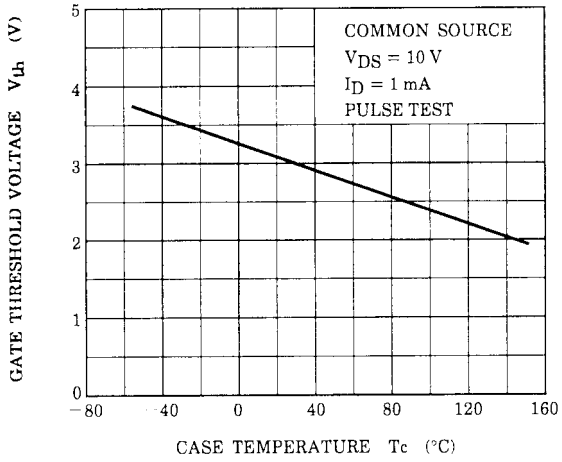

$I_{DR}$ – $V_{DS}$



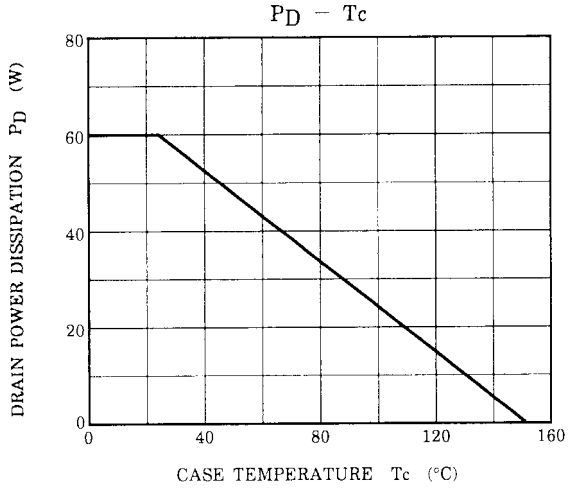

CAPACITANCE – $V_{DS}$



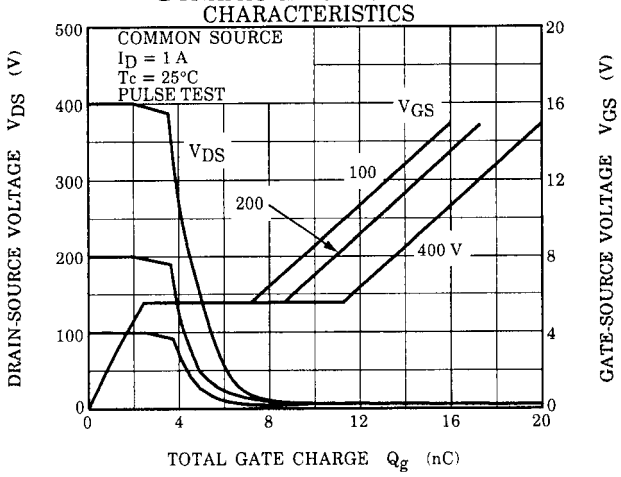

$V_{th}$ – Tc

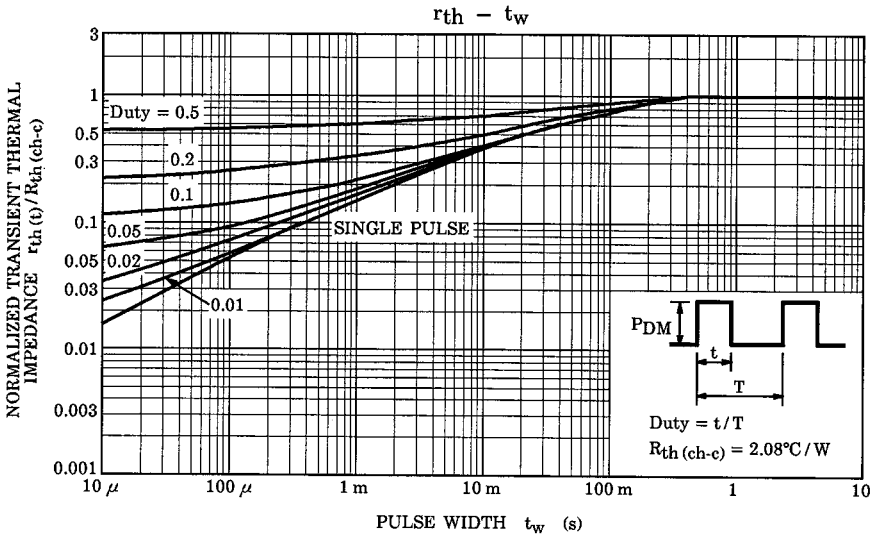


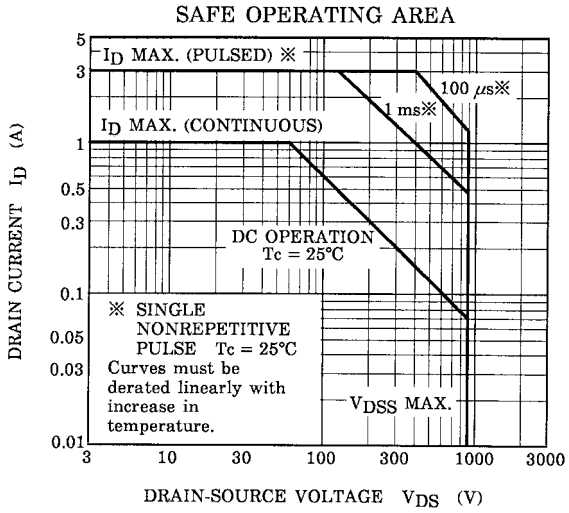

$P_D$ – Tc

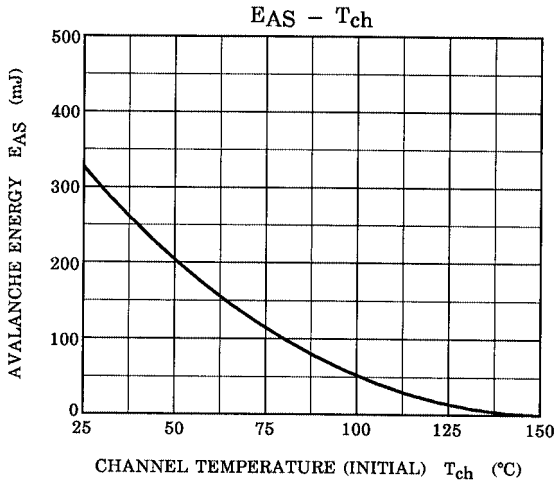


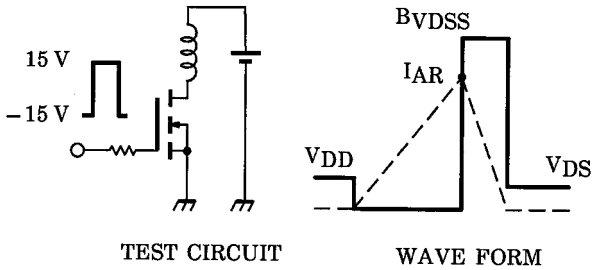

DYNAMIC INPUT / OUTPUT CHARACTERISTICS






$R_G = 25\ \Omega$
$V_{DD} = 90$ V, L = 594 mH

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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